

IN THE SPECIFICATION:

Please amend paragraph two on page 9 as follows:

Figs. 9(A) to 9(C) are typical perspective views ~~Fig. 9 is a typical perspective view~~ of a processing process which uses the invention.

Please amend paragraph 7 on page 9 as follows:

Figs. 14(A) to 14(B) (C) are pattern diagrams of manufacturing processes which relates to the embodiment 1 of the invention, and left diagrams are top views, and right diagrams are cross-section views of a-a' of the left diagrams, respectively.

Please amend paragraph 5 on page 8 as follows:

Fig. 19 is a pattern diagram ~~Figs. 19(A) to (C) are pattern diagrams~~ of manufacturing processes which relates to the embodiment 2 of the invention, and left diagrams are top views, and right diagrams are cross-section views of a-a' of the left diagrams, respectively.

Please amend paragraph 6 on page 8 as follows:

Figs. 20(A) to 20(G) (C) are views which shows an electronic device which relates to an embodiment 4 of the invention.

Please amend paragraph 8 on page 8 as follows:

Figs. 22(A) and 22(B) are views which show ~~Fig. 22 is a view which shows~~ a droplet emitting part of the dot form droplet emitting apparatus of the invention.

Please amend paragraph 1 on page 9 as follows:

Figs. 23(A) to 23(C) are views which show ~~Fig. 23 is a view which shows~~ a bottom surface of the droplet emitting part of the dot form droplet emitting apparatus of the invention.

Please amend paragraph 4 on page 9 as follows:

Figs. 26(A) to 26(D) are pattern diagrams ~~Fig. 26 is a pattern diagram~~ of a process for manufacturing a channel etch type TFT by use of the invention.

Please amend paragraph 5 on page 9 as follows:

Figs. 27(A) to 27(C) are pattern diagrams ~~Fig. 27 is a pattern diagram~~ of a process for manufacturing the channel etch type TFT by use of the invention.